

600 Watt Transient Voltage Suppressor

MP6KE6.8A – MXLP6KE200CA(e3)



Product Overview

The MP6KE6.8A - MXLP6KE200CA series of axial lead 600 watt transient voltage suppressors provide a selection of standoff voltages (V_{WM}) from 5.8 to 171V, with nominal breakdown voltages of 6.8 to 200V. These high-reliability devices are available in either unidirectional or bidirectional versions. RoHS compliant versions are available. These are available with a variety of upscreening options for enhanced reliability. They can protect against the secondary effects of lightning per IEC61000-4-5 and against voltage pulses from inductive switching environments and induced by RF radiation. Since their response time is virtually instantaneous, they can also be used in protection from ESD and EFT per IEC61000-4-2 and IEC61000-4-4.

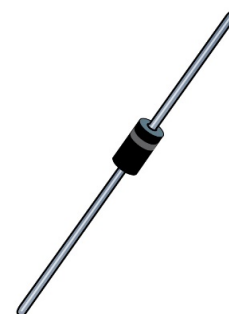
Features

- Available in both unidirectional and bidirectional configurations
- 3σ lot norm screening performed on standby current I_D for all M prefix devices
- 100% surge tested devices
- Suppress transients up to 600 watts at $10\backslash 1000\ \mu s$ (see [Figure 4-1](#))
- Enhanced reliability screening in reference to MIL-PRF-19500 are available. Refer to [High Reliability Non-Hermetic Product Portfolio](#) for more details on the screening options. (See [Part Nomenclature](#) for all options.)
- High reliability controlled devices have wafer fabrication and assembly lot traceability for all M prefix devices
- Moisture classification is level 1 with no dry pack required per IPC/JEDEC J-STD-020F for all M prefix devices
- RoHS compliant versions are available
- Surface mount equivalent packages for PCB mounting are available as MSMBJ5.0A - MXLSMBG170Ae3 (contact Microchip for other options.)

Applications/Benefits

- Available in working standoff voltage (V_{WM}) range 5.8 to 171 volts, with nominal breakdown voltage $V_{(BR)}$ 6.8 to 200 volts
- Economical axial-lead plastic encapsulated TVS series for thru-hole mounting
- Protects sensitive components such as IC's, CMOS, Bipolar, BiCMOS, ECL, DTL, T2L, etc
- Protection from switching transients & induced RFI
- Compliant to IEC 61000-4-2 and IEC 61000-4-4 for ESD and EFT protection respectively.
- Secondary lightning protection per IEC61000-4-5 with 42 ohms source impedance:
 - Class 1: MP6KE6.8A to MXLP6KE130CA
 - Class 2: MP6KE6.8A to MXLP6KE68CA
 - Class 3: MP6KE6.8A to MXLP6KE36CA
 - Class 4: MP6KE6.8A to MXLP6KE18CA
- Secondary lightning protection per IEC61000-4-5 with 12 ohms source impedance:
 - Class 1: MP6KE6.8A to MXLP6KE43CA
 - Class 2: MP6KE6.8A to MXLP6KE22CA

Figure 1. T-18 Package



Also available in:

DO-214AA package

(J-bend surface mount)

[MSMBJ5.0A thru MXLSMBJ170CA](#)

DO-215AA package

(Gull-wing surface mount)

[MSMBG5.0A thru
MXLSMBG170CA](#)

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1. Maximum Ratings

Table 1-1. Maximum Ratings at 25 °C Unless Otherwise Noted

Parameters/Test Conditions		Symbol	Value	Unit
Junction and storage temperature		T _J and T _{STG}	−65 to +150	°C
Thermal resistance, junction to lead ¹		R _{ΘJL}	25	°C/W
Thermal Resistance, junction to ambient ²		R _{ΘJA}	85	°C/W
Peak pulse power dissipation at 10/1000μs ³		P _{PP}	600	W
Average power dissipation	at T _L = 25 °C ¹ at T _A = 25 °C ²	P _D	5 1.47	W
T _{clamping} (0 volts to V _(BR) min, theoretical)	Unidirectional Bidirectional	—	< 100 < 5	ps ns
Solder temperature at 10 seconds		—	260	°C

Notes:

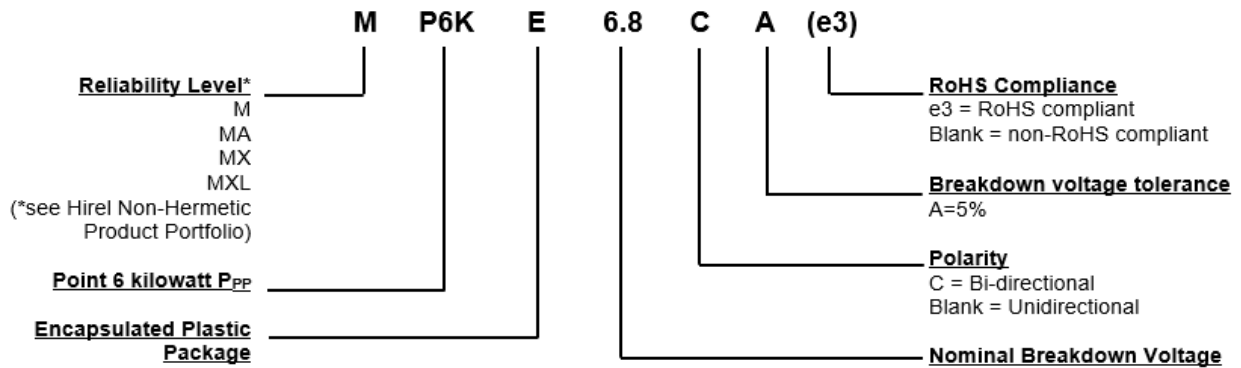
1. At 3/8 (10mm) lead length from body
2. Mounted on FR4 PC board with 4 mm² (1 oz) copper pads and track width 1 mm, length 25 mm
3. With impulse repetition rate (duty factor) of 0.01 % or less (see [Figure 4-1](#), [Figure 4-2](#), and [Figure 4-3](#) for t_W waveform and derating effects)

1.1 Mechanical Packaging

- Case: Void-free transfer molded thermosetting epoxy body meeting UL94V-0
- Terminals: Tin-lead or RoHS compliant annealed matte-tin plating. Solderable per MIL-STD-750, method 2026.
- Marking: Reliability level, part number, date code
- Polarity: Cathode indicated by band. Bidirectional not marked.
- Tape and Reel option: Standard per EIA-296 (add “TR” suffix to part number). Consult factory for quantities.
- Weight: Approximately 0.7 grams
- See [Package Dimensions](#)

2. Part Nomenclature

Figure 2-1. Part Nomenclature



2.1 Symbols and Definitions

Table 2-1. Symbols and Definitions

Symbol	Definition
$\alpha_{V(BR)}$	Temperature coefficient of breakdown voltage: The change in breakdown voltage divided by the change in temperature that caused it expressed in $\%/^{\circ}\text{C}$ or $\text{mV}/^{\circ}\text{C}$.
C_T	Total capacitance: The total small signal capacitance between the diode terminals of a complete device.
$I_{(BR)}$	Breakdown current: The current used for measuring breakdown voltage $V_{(BR)}$.
I_D	Standby current: The current through the device at working standoff voltage.
I_{PP}	Peak impulse current: The peak current during an impulse.
P_{PP}	Peak pulse power: The peak power that can be applied for a specific pulse width and waveform. The product of I_{PP} and V_C .
$V_{(BR)}$	Breakdown voltage: The voltage across the device at a specified current $I_{(BR)}$ in the breakdown region.
V_C	Clamping voltage: The voltage across the device in a region of low differential resistance during the application of an impulse current (I_{PP}) for a specified waveform.
V_{WM}	Working standoff voltage: The maximum-rated value of DC or repetitive peak positive cathode-to-anode voltage that may be continuously applied over the standard operating temperature.

3. Electrical Characteristics

Table 3-1. Electrical Characteristics at 25 °C Unless Otherwise Stated¹⁻⁴

Part Number	Breakdown Voltage $V_{(BR)}$ at $I_{(BR)}$			Working Standoff Voltage V_{WM}	Max Standby Current I_D at V_{WM}	Max Clamping Voltage V_C at I_{PP}	Peak Pulse Current at 10/1000 μs (see Figure 4-2) I_{PP}	Temperature Coefficient of $V_{(BR)}$ $\alpha_{V(BR)}$
	V_{MIN}	V_{MAX}	mA	V	μA	V	A	%/°C
MP6KE6.8(C)A	6.45	7.14	10	5.8	1000	10.5	57	0.057
MP6KE7.5(C)A	7.13	7.88	10	6.4	500	11.3	53	0.061
MP6KE8.2(C)A	7.79	8.61	10	7.02	200	12.1	50	0.065
MP6KE9.1(C)A	8.65	9.55	1	7.78	50	13.4	45	0.068
MP6KE10(C)A	9.5	10.5	1	8.55	10	14.5	41	0.073
MP6KE11(C)A	10.5	11.6	1	9.4	5	15.6	38	0.075
MP6KE12(C)A	11.4	12.6	1	10.2	5	16.7	36	0.078
MP6KE13(C)A	12.4	13.7	1	11.1	5	18.2	33	0.081
MP6KE15(C)A	14.3	15.8	1	12.8	1	21.2	28	0.084
MP6KE16(C)A	15.2	16.8	1	13.6	1	22.5	27	0.086
MP6KE18(C)A	17.1	18.9	1	15.3	1	25.2	24	0.088
MP6KE20(C)A	19	21	1	17.1	1	27.7	22	0.090
MP6KE22(C)A	20.9	23.1	1	18.8	1	30.6	20	0.092
MP6KE24(C)A	22.8	25.2	1	20.5	1	33.2	18	0.094
MP6KE27(C)A	25.7	28.4	1	23.1	1	37.5	16	0.096
MP6KE30(C)A	28.5	31.5	1	25.6	1	41.4	14.4	0.097
MP6KE33(C)A	31.4	34.7	1	28.2	1	45.7	13.2	0.098
MP6KE36(C)A	34.2	37.8	1	30.8	1	49.9	12	0.099
MP6KE39(C)A	37.1	41	1	33.3	1	53.9	11.2	0.100
MP6KE43(C)A	40.9	45.2	1	36.8	1	59.3	10.1	0.101
MP6KE47(C)A	44.7	49.4	1	40.2	1	64.8	9.3	0.101
MP6KE51(C)A	48.5	53.6	1	43.6	1	70.1	8.6	0.102
MP6KE56(C)A	53.2	58.8	1	47.8	1	77	7.8	0.103
MP6KE62(C)A	58.9	65.1	1	53	1	85	7.1	0.104
MP6KE68(C)A	64.6	71.4	1	58.1	1	92	6.5	0.104
MP6KE75(C)A	71.3	78.8	1	64.1	1	103	5.8	0.105
MP6KE82(C)A	77.9	86.1	1	70.1	1	113	5.3	0.105
MP6KE91(C)A	86.5	95.5	1	77.8	1	125	4.8	0.106
MP6KE100(C)A	95	105	1	85.5	1	137	4.4	0.106
MP6KE110(C)A	105	116	1	94	1	152	3.4	0.107
MP6KE120(C)A	114	126	1	102	1	165	3.6	0.107
MP6KE130(C)A	124	137	1	111	1	179	3.3	0.107
MP6KE150(C)A	143	158	1	128	1	207	2.9	0.108
MP6KE160(C)A	152	168	1	136	1	219	2.7	0.108

.....continued

Part Number	Breakdown Voltage $V_{(BR)}$ at $I_{(BR)}$			Working Standoff Voltage V_{WM}	Max Standby Current I_D at V_{WM}	Max Clamping Voltage V_C at I_{PP}	Peak Pulse Current at 10/1000 μs (see Figure 4-2) I_{PP}	Temperature Coefficient of $V_{(BR)}$ $\alpha_{V(BR)}$
	V_{MIN}	V_{MAX}	mA	V	μA	V	A	%/°C
MP6KE170(C)A	161	179	1	145	1	234	2.6	0.108
MP6KE180(C)A	171	189	1	154	1	246	2.4	0.108
MP6KE200(C)A	190	210	1	171	1	274	2.2	0.108

Consult factory for higher voltages.

Notes:

1. Normal selection criteria for TVS devices is by working standoff voltage (V_{WM}) and should be equal or greater than DC or continuous peak operating voltage.
2. TVS devices are tested to maximum peak pulse current (I_{PP}) with clamping voltage monitored. This surge capability is one of the most significant electrical characteristics of the device and should be considered as part of customer quality inspections.
3. Bidirectional devices are indicated with a CA suffix after part number. Bidirectional capacitance is half that shown in [Figure 4-4](#) at zero volts. For Bidirectional types having V_{WM} of 8 volts and under, the I_D leakage current is doubled.
4. For unidirectional devices, the forward voltage (V_F) is 3.5 volts maximum at 100 Amps peak for 8.3 ms half-sine wave.

4. Graphs

Figure 4-1. Peak Pulse Power Vs. Pulse Time

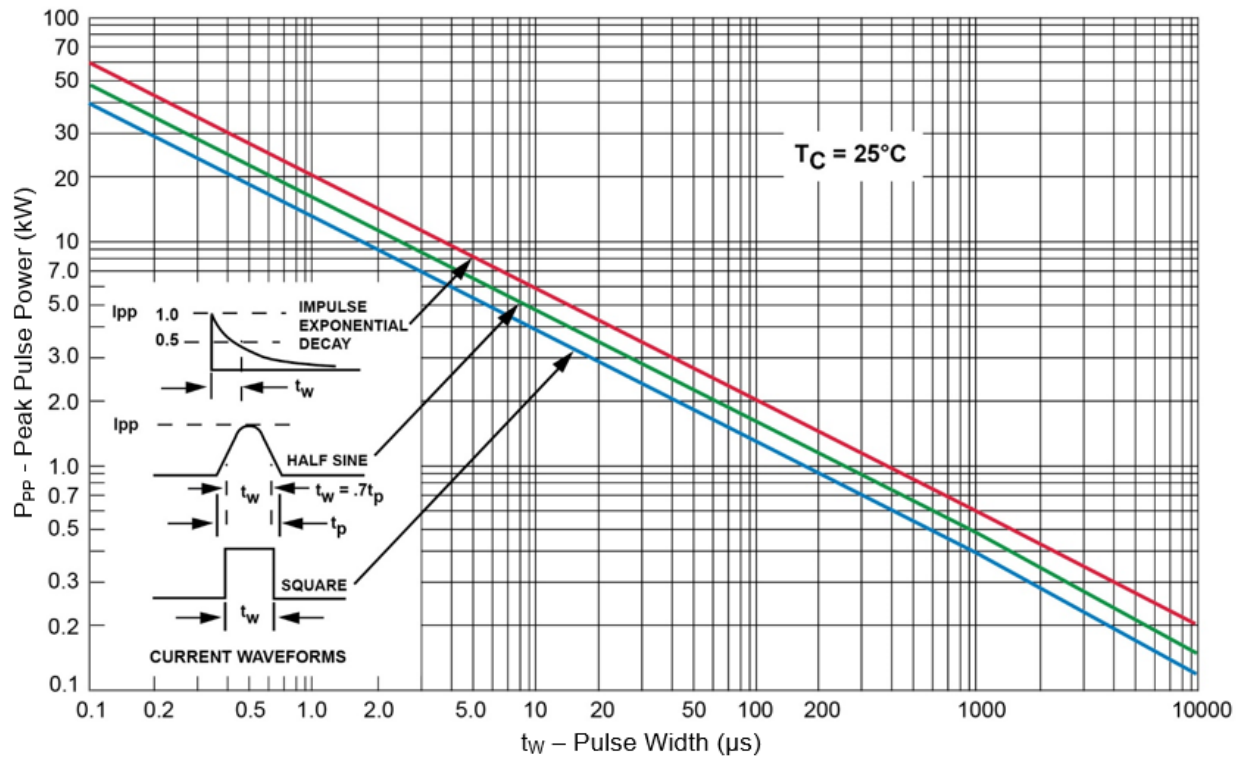


Figure 4-2. Pulse Waveform for 10/1000 μs Exponential Surge

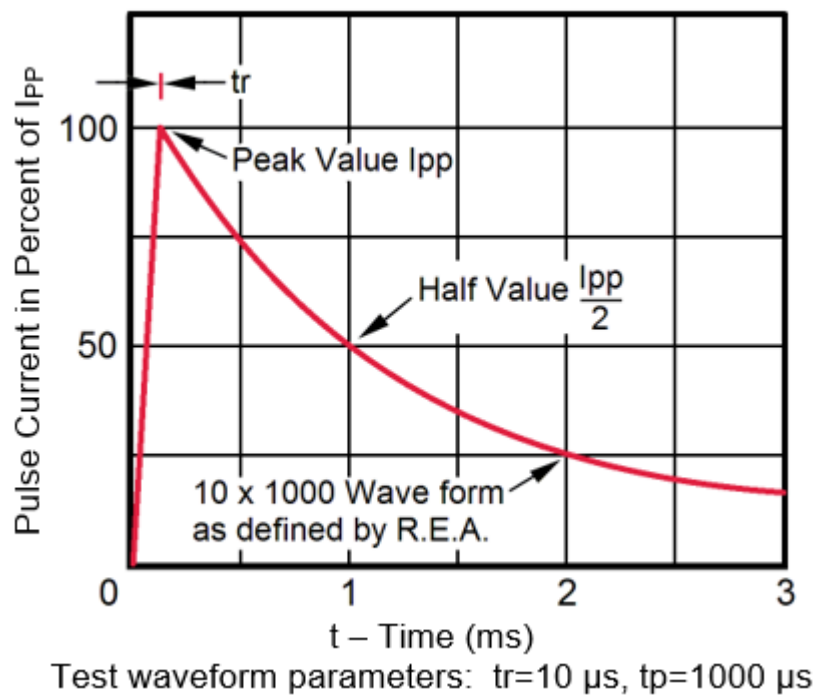


Figure 4-3. Derating Curve

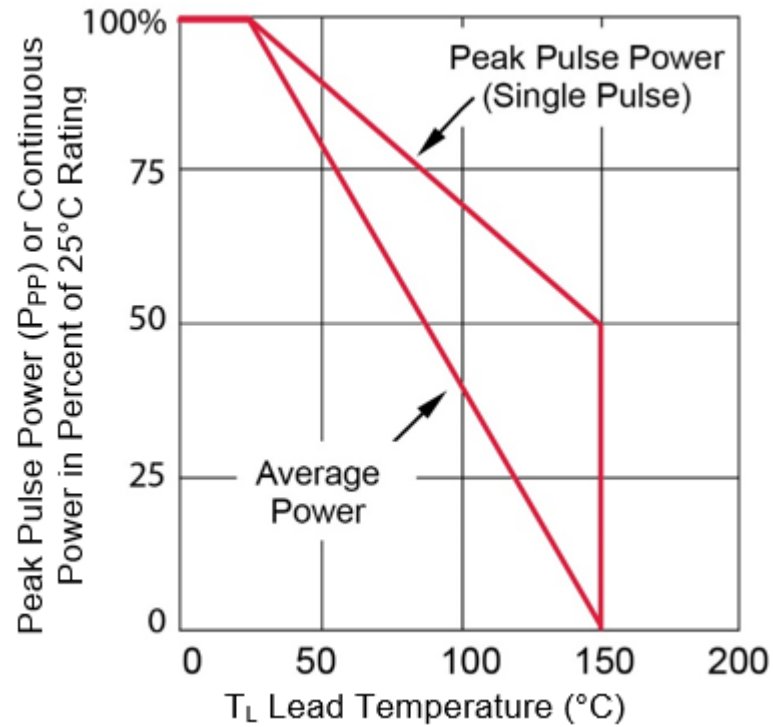
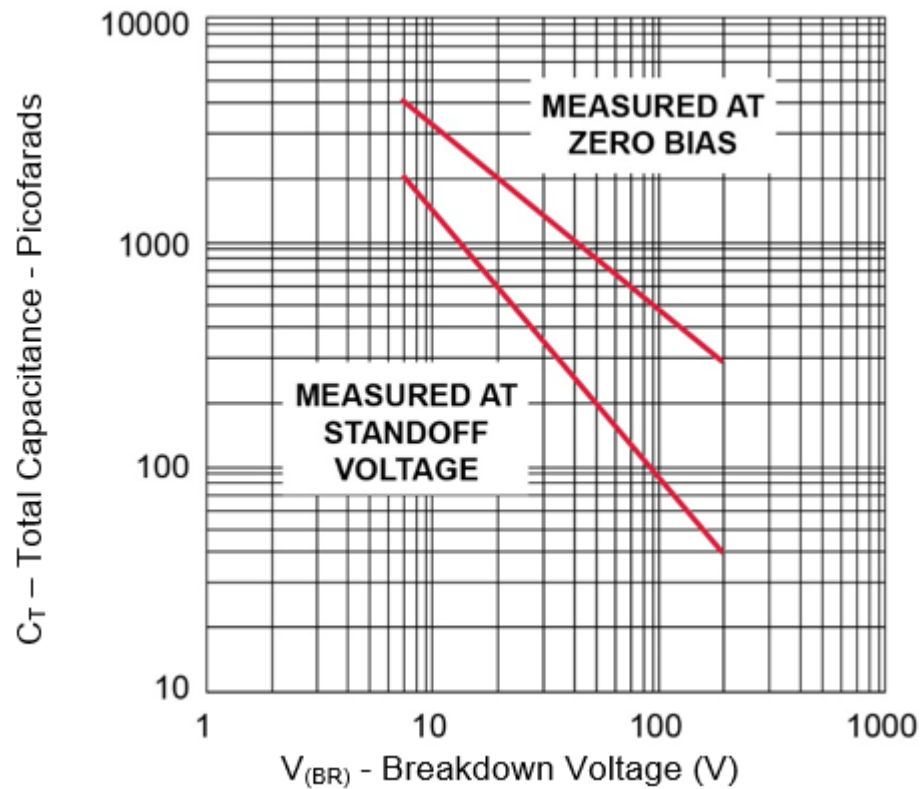


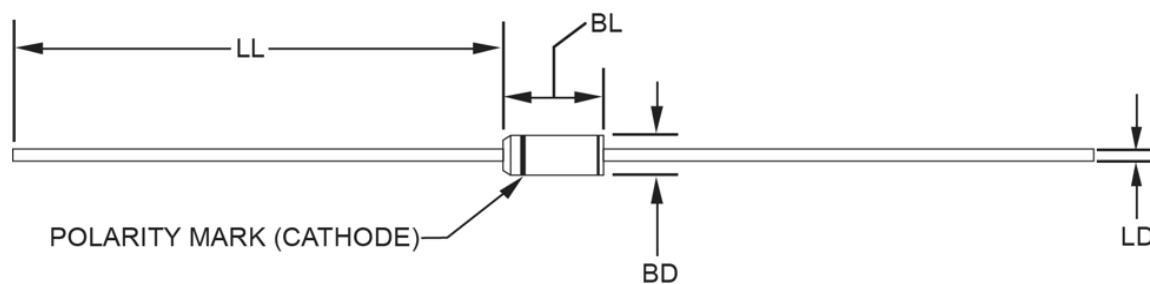
Figure 4-4. Typical Capacitance Vs. Breakdown Voltage



Bidirectional capacitance is half that shown.

5. Package Dimensions

Figure 5-1. Package Dimensions¹



Note:

1. Cathode indicated by band.

Dim.	Dimensions			
	Inches		Millimeters	
	Min.	Max.	Min.	Max.
LL	1.00	—	25.4	—
BL	0.330	0.350	8.39	8.89
BD	0.130	0.145	3.31	3.68
LD	0.038	0.042	0.97	1.06

6. Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

Revision	Date	Description
A	01/2024	Initial revision.

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